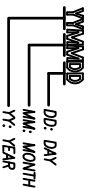


REV.	ECN NO. OR DESCRIPTION	REVISED	DATE
A	T080409-2A	Mark-Wang	2008.01.01
B	ECN NO. S090318	Sanning	2009.04.30
C	ECN NO. S100527	Ryan	2010.05.25

SPECIFICATIONS:

- RATING: DC 20V 4A
- INSERTION FORCE: 3.0KG MAX
- WITHDRAWAL FORCE: 1.0KG-3.0KG
- INSULATION RESISTANCE BETWEEN ANY ADJACENT TERMINALS SHALL NOT BE LESS THAN 100 MEGOHMS BY 500 VOLTS MEGGER.
- JACK SHALL WITHSTAND 250 VOLTS BETWEEN ANY ADJACENT TERMINAL FOR ONE MINUTE.
- CONTACT RESISTANCE SHALL NOT EXCEED 30mΩ.
- JACK SHALL WITHSTAND 5,000 CYCLES OF INSERTION AND WITHDRAWAL WITH TESTING PLUG AND CONTACT RESISTANCE SHALL NOT EXCEED 100MΩ.
- MEASURING CONDITION:
 - TEMPERATURE: FROM 5°C TO 35°C.
 - RELATIVE HUMIDITY: FROM 40% TO 85%
- ENVIRONMENTAL SPECIFICATIONS:
 - 8.1 HUMIDITY TEST: HUMIDITY 90% TO 95% TEMPERATURE 40°C ± 2°C FOR 96 HOURS.
 - 8.2 HEAT TEST: TEMPERATURE 70°C ± 2°C (HUMIDITY BELOW 50%) FOR 96 HOURS.
 - 8.3 COLD TEST: TEMPERATURE -40°C ± 2°C FOR 96 HOURS.
- SOLDERABILITY TEST: THE TERMINATION IS AT LEAST 95% COVERED BY A CONTINUOUS NEW SOLDER COATING.
- TEST CONDITION: DIP IN MOLTEN SOLDER FOR 5 Sec. AT 265±5°C (TERMINATION SHALL BE IMMERSED IN FLUX BEFORE TEST)
- PACKING: TAPE & REEL.
- SOLDERING CONDITION: WAVE SOLDERING / IR REFLOW.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPECIFICATION*
- GREEN PRODUCT IDENTIFICATION MARK ON JACK:
- GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR LEAD FREE PROCESS.
- PRINTED DATE CODE "YMMDD" ON TOP OF CONNECTOR.



G	GROUNDING SPRING	1	STAINLESS 0.1t	N/A
F	SHIELDING	1	BRASS 0.2t	Ni 60u" Min
E	PIN	1	BRASS BAR	Ag 20u" Min
D	TERMINAL	1	STAINLESS 0.3t	N/A
C	SHUNT TERMINAL	1	BRASS 0.3t	Ag 20u" Min
B	TIP SPRING	1	COPPER ALLOY 0.3t	Ag 20u" Over Ni20u"
A	BODY	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK
NO		DESCRIPTION		QTY
UNLESS OTHERWISE SPECIFIED TOLERANCES		MATERIAL		PLATING & COLOR
DECIMALS:		ANGLES:	TITLE	
X	±0.5	X	±2°	DC POWER JACK
X,X	±0.3	X,X	±1°	RYAN PART NO. ZDC-G756-Q34
X,XX	±0.2			CHKD Lussen SCALE:N/A UNIT: mm
				APVD MAX SIZE: A3 SHEET: 1 OF 1 REV: C
CUSTOMER COPY				

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